# SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74S174, SN74S175, HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

SDLS068

DECEMBER 1972-REVISED MARCH 1988

'174, 'LS174, 'S174 . . . HEX D-TYPE FLIP-FLOPS '175, 'LS175, 'S175 . . . . QUADRUPLE D-TYPE FLIP-FLOPS

- '174, 'LS174, 'S174 Contain Six Flip-Flops with Single-Rail Outputs
- 175, 'LS175, 'S175 Contain Four Flip-Flops with Double-Rail Outputs
- Three Performance Ranges Offered: See Table Lower Right
- Buffered Clock and Direct Clear Inputs
- Individual Data Input to Each Flip-Flop
- Applications include:

   Buffer/Storage Registers
   Shift Registers

  Pattern Generators

#### description

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These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic. All have a direct clear input, and the '175, 'LS175, and 'S175 feature complementary outputs from each flip-flop:

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output.

These circuits are fully compatible for use with most TTL circuits.

FUNCTION TABLE

11	OUTPUTS			
CLEAR	CLOCK	D	Q	ō۲
L	x	X	L,	Н
н	†	н	н	L
Н	t	L	L	Н
H	L	x	a <sub>o</sub>	$\bar{\mathbf{q}}_0$

H = high level (steady state)

L = low level (steady state)

X = irrelevant

1 - transition from low to high level

 $Q_0$  = the level of Q before the indicated steady-state input conditions were established.

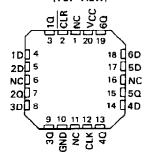
1 = '175, 'LS175, and 'S175 only

	TYPICAL	TYPICAL
TYPES	MAXIMUM	POWER
ITPES	CLOCK	DISSIPATION
	FREQUENCY	PER FLIP-FLOP
174, 175	35 MHz	38 mW
'LS174, 'LS175	40 MHz	14 mW
'S174. 'S175	110 MHz	75 mW

SN54174, SN54LS174, SN54S174...J OR W PACKAGE SN74174...N PACKAGE SN74LS174, SN74S174...D OR N PACKAGE (TOP VIEW)

٠,	•		-,	
CLR [	ī	U <sub>16</sub>		Vcc
10 💆	2	15	Ц	6Ω
ם נ 🗀	3	14		6D
2D 🛚	4	13		5D
20 🛚	5	12	2	5Q
3D 🗌	6	11		4D
30 🛚	7	10	╝	4Q
SND 🛚	8	9		CLK

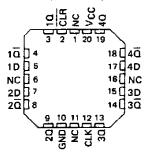
SN54LS174, SN54S174 . . . FK PACKAGE (TOP VIEW)



SN54175, SN54LS175, SN54S175...J OR W PACKAGE SN74175...N PACKAGE SN74LS175, SN74S175...D OR N PACKAGE (TOP VIEW)

CLR []	U <sub>16</sub>	Dvcc
10.□2	15	<b>□</b> 40
10 □3	14	D 40
10 □4	13	<b>□</b> 40
2D 🛮 5	12	□ 3D
20 □6	11	□зā
20 🛛 7	10	<b>□30</b>
GND □8	9	🛘 clk

SN54LS175, SN54S175 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

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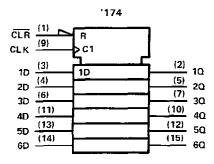


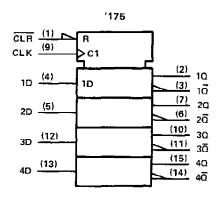
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#### logic symbols †

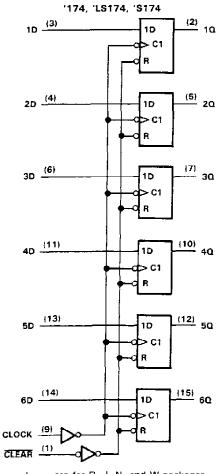
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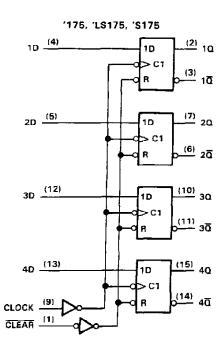




<sup>&</sup>lt;sup>1</sup>These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

#### logic diagrams (positive logic)





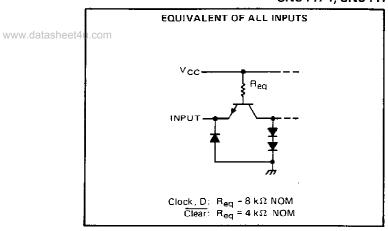
Pin numbers shown are for D, J, N, and W packages.

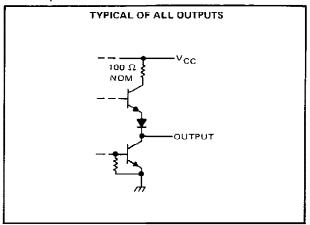


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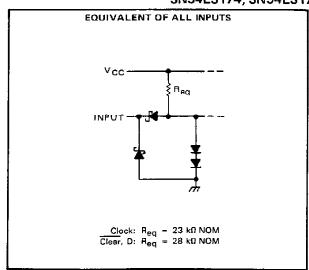
## schematics of inputs and outputs

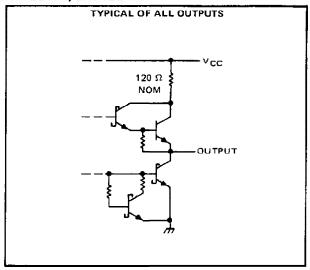
# SN54174, SN54175, SN74174, SN74175



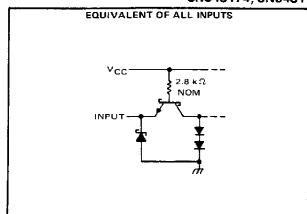


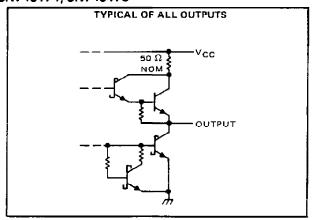
SN54LS174, SN54LS175, SN74LS174, SN74LS175





SN54S174, SN54S175, SN74S174, SN74S175







## SN54174, SN54175, SN74174, SN74175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

abso	ute maximum ratings over operating free-air temperature range (unless otherwise noted)
	Supply voltage, V <sub>CC</sub> (see Note 1)
	Input voltage
www.datasheet4u.com	Operating free-air temperature range: SN54174, SN54175 Circuits —55°C to 125°C
www.dataonect-a.com	SN/4174, SN74175 Circuits
	Storage temperature range
NOTE	1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

		SN54	174, SN	54175	SN74174, SN74175			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-800			-800	μА
Low-level output current, IOL		1		16			16	mA
Clock trequency, fclock		0		25	0		25	MHz
Width of clock or clear pulse, t <sub>W</sub>		20			20			ns
Control time t	Data input	20			20			កន
Setup time, t <sub>SU</sub>	Clear inactive-state	25			25			ns
Data hold time, th		5			5	-		ns
Operating free-air temperature, TA		-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIO	NS†	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage			" "		0.8	٧
Vik	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 i	nΑ			-1.5	٧
۷Он	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 \ V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -8		2.4	3.4		٧
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16	-		0.2	0.4	٧
11	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>1</sub> = 5.5 \	/			1	mΑ
ΉΗ	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 \	/			40	μΑ
ηլ	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 \	,	T		-1.6	mA
		14 546.34	SN54'	20		-57	
los	Short-circuit output current <sup>§</sup>	V <sub>CC</sub> = MAX	SN74*	-18		-57	mΑ
		W - MANY Con Night	174	1	45	65	
CC	Supply current	V <sub>CC</sub> = MAX, See Note :	175		30	45	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

## switching characteristics, VCC = 5 V, TA = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		25	35		MHz
	Propagation delay time, low-to-high-level output from clear			40		
tPLH	tPLH (SN54175, SN74175 only)	CL = 15 pF,		16	25	ns
†PHL	Propagation delay time, high-to-low-level output from clear	R <sub>L</sub> = 400 Ω, See Note 3		23	35	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output from clock	ace More a		20	30	пѕ
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^{\</sup>ddagger}$ All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25°C.

<sup>\$</sup>Not more than one output should be shorted at a time.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, then 4.5 V, is applied to clock.

## SN54LS174, SN54LS175, SN74LS174, SN74LS175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

abs	solute maximum ratings over operating free-air temperature range (unless otherwise noted)
	Supply voltage, VCC (see Note 1)
	Input voltage
	Operating free-air temperature range: SN54LS174, SN54LS175 Circuits
www.datasheet4u.con	SN74LS174, SN74LS175 Circuits
	Storage temperature range
NO <sup>-</sup>	FE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

		SN54LS174			SN74LS174			
		SI	N54LS1	75	SN74LS175			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-400			-400	μА
Low-level output current, IQL				4			8	mА
Clock frequency, felock		0		30	0		30	MHz
Width of clock or clear pulse, tw		20			20			ns
Control	Data input	20			20			ns
Setup time, t <sub>su</sub>	Clear inactive-state	25			25			ns
Data hold time, th		5			5			ns
Operating free-air temperature, TA		-55		125	0		70	3°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†		SN54LS174 SN54LS175		SN74LS174 SN74LS175			UNIT		
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$v_{IH}$	High-level input voltage				2			2	-		٧
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			-1.5	٧
Voн	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>(L</sub> max,		4	2.5	3.5		2.7	3.5		٧
VOL	Low-level output voltage	VCC = MIN,	•••	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	>
- OL		Vir = Vir wax		I <sub>OL</sub> = 8 mA					0.35	0.5	
Ц	Input current at maximum input voltage	VCC = MAX.	V <sub>I</sub> = 7 V				0.1			0.1	mA
ЧН	High-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	μА
1 <sub>1</sub> L	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				-0.4	-		-0.4	mΑ
los	Short-circuit output current §	V <sub>CC</sub> = MAX			-20		-100	-20		-100	mΑ
loc	Supply current	VCC = MAX,	See Note 7	'LS174		16	26		16	26	A
Icc	ooppiy content	*CC   IIAA,	CC = MAX, See Note 2	'LS175		11	18		11	18	mΑ

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	'LS174			'LS175			
PAGAMETER		MIN	TYP	MAX	MIN	TYP	MAX	UNIT
f <sub>max</sub> Maximum clock frequency		30	40		30	40		MHz
TPLH Propagation delay time, low-to-high-level output from clear	C <sub>L</sub> = 15 pF.					20	30	ns
tpht Propagation delay time, high-to-low-level output from clear	$R_L = 2 k\Omega$ ,		23	35		20	30	ns
tplH Propagation delay time, low-to-high-level output from clock	See Note 3		20	30		13	25	ns
tpHL Propagation delay time, high-to-low-level output from clock			21	30		16	25	ПS

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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<sup>‡</sup>All typical values are at V<sub>CC</sub> - 5 V, T<sub>A</sub> = 25 C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, then 4.5 V, is applied to clock.

## SN54S174, SN54S175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

abso	lute maximum ratings over operating free-air temperature range (unless otherwise noted)
	Supply voltage, V <sub>CC</sub> (see Note 1)
	Input voltage
	Operating free-air temperature range: SN54S174, SN54S175 Circuits
www.datasheet4u.com	SN74S174, SN74S175 Circuits
	Storage temperature range
NOTE	1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN54S174, SN54S175			SN74S174, SN74S175			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-1			1	mΑ
Low-level output current, IOL				20			20	mA
Clock frequency, fclock		0	***	75	0		75	MHz
Di tan middle a	Clack	7			7			
Pulse width, t <sub>w</sub>	Clear	10			10			пs
	Data input	5			5	•		
Setup time, t <sub>su</sub>	Clear inactive-state	5			5			ns
Data hold time, t <sub>h</sub>		3			3		_	ns
Operating free-air temperature, TA		-55		125	0		70	°Ç

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>			TYP‡	MAX	UNIT
V <sub>1H</sub> High-level input voltage				2			V
VIL	Low-level input voltage		<u>.</u>			0.8	V
Vik	Input clamp voltage	VCC = MIN, II = -18 mA				-1.2	٧
VOH	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>1H</sub> = 2 V,	SN54S'	2.5	3.4	-	
		V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	SN745'	2.7	3.4		\ \
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,	-			0.5	
		V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA		ļ		Ų.5	٧
Ιι	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V				1	mΑ
чн	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.7 V				50	μΔ
IIL.	Low-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 0.5 V				-2	mΑ
los	Short-circuit output current§	V <sub>CC</sub> - MAX		-40		-100	mA
lcc	O	V <sub>CC</sub> = MAX, See Note 2 '174 '175	174		90	144	
	Supply current		175		60	96	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		75	110		MHz
tPLH	Propagation delay time, low-to-high-level $\overline{\Omega}$ output from clear (SN54S175, SN74S175 only)	C <sub>L</sub> = 15 pF,		10	15	ns
<sup>[PHL]</sup>	Propagation delay time, high-to-low-level Q output from clear	R <sub>L</sub> = 280 Ω, See Note 3		13	22	ns
tPLH	Propagation delay time, low-to-high-level output from clock	266 More 2		8	12	ns
<sup>‡</sup> PHL	Propagation time, high-to-low-level output from clock			11.5	17	пs

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>^{\</sup>dagger}$ All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25°C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I<sub>CC</sub> is measured after a momentary ground, than 4.5 V, is applied to clock.

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